Electronic Patent Application Fee Transmittal							
Application Number:	09546174						
Filing Date:	11-Apr-2000						
Title of Invention:	HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS						
First Named Inventor/Applicant Name:	Chih-Chien Liu						
Filer:	William H. Wright/Lillian Rodriguez						
Attorney Docket Number:	JIA 462C1						
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